	Туре	L#	Hits	Search Text	DBs	Time Stamp	C o m m e nt	Er ror De fin iti on	rs
1	BRS	L1	0	(clean\$3 or etch\$3) same semicondcutor same (oxoethylene or oxypropylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 15:11			0
2	BRS	L8	170	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 17:58			0
3	BRS	L15	0	8 and "19991004"	USPAT; US-PGPUB EPO; JPO; DERWENT; IBM_TDB	11.18			0
4	BRS	L22	136	8 and @pd<=19991004	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	2002/06/01 13:22			0
5	BRS	5 L29	2	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same (H2O or water) same ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide))	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	12:00			0
6	BRS	S L30	3 0	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same (H2O or water) same ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide)) same ("hydrogen peroxide" or H2O2 or peroxide)	US-PGPUI	3; 2002/06/01 13:09			
7	BR	S L4	3 22	(clean\$3 or etch\$3) and (oxoethylene or oxypropylene) and (H2O or water) and ((TMAH or ("tetramethyl ammonium" or sodium or potassium or ammonium) adj hydroxide)) and ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	. 2002/00/0	1	47.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1	***************************************

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	C o m m e nt	Er ror De fin iti on	ro
}	BRS	L5	50	7	43 and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 13:11			0
9	BRS	SL	57	165	43 and @pd<=19991004	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	2002/06/01 14:29			0
10	BRS	SL	64	4	(clean\$3 or etch\$3) same (oxoethylene or oxypropylene) same ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	3, 2002/06/01 13:27			0
11	BR	SL	.71	46	(clean\$3 or etch\$3) and (oxoethylene or oxypropylene) and ("hydrogen peroxide" or H2O2 or peroxide)	USPAT; US-PGPUI EPO; JPO; DERWENT IBM_TDB				0
12	2 BR	s	L92	2 33	1 71 and @pd<=19991004	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB		1		0
1:	3 BF	≀s	L9!	9 0	92 and 438/\$.ccls.	USPAT; US-PGPU EPO; JPC DERWEN IBM_TDB	T; 10.30	1		
1	4 Bi	RS	L1	06 1	7 92 and 134/\$.ccls.	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDE	1T; 10.43	01		
	15 B	RS	L	113 1	92 and 216/\$.ccls.	USPAT; US-PGP EPO; JP DERWE IBM_TDI	NT; 10.47	01		

	Туре	L	_#	H	its		Search Text	DBs	Tin	ne Stamp	C o m m e nt	fin	13
6	BRS	<u> </u>	.12	0 3	8	92	and 252/\$.ccls.	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	, I16	02/06/01 :51			0
7	BR	s l	_12	27	17	10	6 and @pd<=19991004	USPAT; US-PGPU EPO; JPC DERWEN IBM_TDB	', T; 14	002/06/01 1:38			0
18	BR	S	L1	34	1	1	13 and @pd<=19991004	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDE	ίΤ; ¹	002/06/01 6:30			0
19	BF	RS	L1	41	38	1	20 and @pd<=19991004	USPAT; US-PGPI EPO; JPI DERWEI IBM_TDI	NT; 1	002/06/0′ 4:40			0
20	BI	 RS	L	148	97	, [clean\$3 or etch\$3) same composition or pH or component o concentration) same (variable or parameter) same semiconductor	USPAT; US-PGP EPO; JP DERWE IBM_TD	NT;	2002/06/0 16:12	1		
2	1 B	RS	SL	15	5 72	21	(clean\$3 or etch\$3) same (composition or pH or component) same (variable or parameter or vary\$3 or chang\$3 or alter\$6) sam semiconductor	EPU; Jr	PUB; PO; NT;	2002/06/0 16:16)1		
2	2 E	3RS	SL	_16	123	23	(clean\$3 or etch\$3) same (composition or pH or component mole) same (variable or paramete or vary\$3 or chang\$3 or alter\$6) same semiconductor	USPAT or US-PG r EPO; J DERW IBM_TI	PUB; PO; ENT;	2002/06/ 16:31	D1		
2	23	BR	S	L1(69/7	796	162 and @pd<=19991004	USPAT US-PG EPO; J DERW IBM_T	PUB PO; ENT	2002/06/ 16:33	01		

	Туре	L#	 	lits	Search Text	DBs	Time Stamp	C o m m e nt	 Er ro rs
24	BRS	L17	'66	623	(clean\$3 or etch\$3) same (component or mole) same (variable or parameter or vary\$3 or chang\$3 or alter\$6) same semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 16:33		0
25	BRS	L18	33	370	176 and @pd<=19991004	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 16:33		0
26	BRS	L1	90	3	183 and 438/745	USPAT; US-PGPUB EPO; JPO; DERWENT; IBM_TDB	2002/06/01 16:35		0
27	BRS	S L1	97	106	183 and 438/\$.ccls.	USPAT; US-PGPUB EPO; JPO; DERWENT IBM_TDB	; 2002/06/01 , 16:36		0
28	BRS	S L2	204	110	183 and 134/\$.ccls.	USPAT; US-PGPUE EPO; JPO; DERWENT IBM_TDB	3; 2002/06/01 -, 16:45		C
29	BR	S L	21	1 36	183 and 216/\$.ccls.	USPAT; US-PGPUI EPO; JPO; DERWEN IBM_TDB	3; 2002/06/0 ¹ 16:48	1	
30) BR	SL	.21	8 26	4 183 not 197	USPAT; US-PGPU EPO; JPO DERWEN IBM_TDB	B; 2002/06/0 T; 16:49	1	
3	1 BF	RS L	_22	25 13	3 211 not 197	USPAT; US-PGPU EPO; JPC DERWEN IBM_TDB	T; 10.43)1	

	Туре	L#	Hits	Search Text	DBs	Time Stamp	C o m m e nt s	Er ror De fin iti on	Er ro rs
32	BRS	L232	11	183 and 252/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/01 17:00			0